ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention

Molded Stiffener for Thin Substrates

Application Number:

10/077554

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Confirmation Number:

3265

First Named Applicant:

Chad Cobbley MTI-31591

Attorney Docket Number:

2814

Art Unit: Examiner:

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Examiner.

Hoa B Trinh

Search string:

(6599365 or 6584897 or 6440777).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

| init | Cite.No. | Patent No. | Date | Patentee | Kind | Class | Subclass |
|----------|----------|------------|------------|----------------|------|-------|----------|
| W | 1 | 6599365 | 2003-07-29 | Jiang et al. | B1 | 118 | 504 |
| \sqcap | 2 | 6584897 | 2003-07-01 | Cobbley et al. | B2 | 101 | 127 |
| \sqcap | 3 | 6440777 | 2002-08-27 | Cobbley et al. | B2 | 438 | 118 |

Signature

| Examiner Name | , Date | | |
|---------------|---------|--|--|
| Vieto June | 6 26/06 | | |